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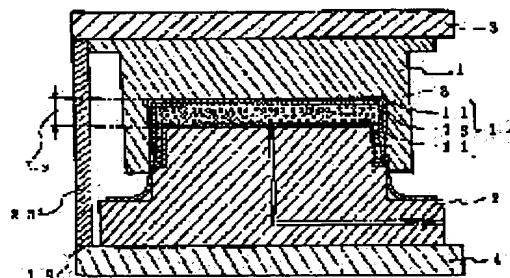
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## (54) MANUFACTURE OF COMPOSITE FOAM -MOLDED PRODUCT

### (57)Abstract:

**PURPOSE:** To obtain a light-weight, highly rigid composite foam-molded product by regulating top and bottom forces to have a specified mold space with the aid of a mold space adjusting material in a very short period of time and expanding a resin composition.

**CONSTITUTION:** A skin material A is set between a top and a bottom forces 1, 2. After keeping a specified space between the forces, a polypropylene resin composition containing a foaming agent, which has been melted at a predetermined temperature, is introduced into a space between the bottom force 2 and the skin material, 8. At the same time, the top force 1 is lowered down at a predetermined speed to clamp the forces until the forces have a predetermined space, and a base material layer, which has not yet been expanded, is integrated with the skin material 8 simultaneously with the shaping of a base material shape. In a period of 0.5 to 5 seconds, the top force 1 is elevated, and it is then lowered until a space L3 between the top and bottom forces 1, 2 is within a range satisfying a formula  $-t_2+t_3 \times 1.1 \leq L_3 \leq t_2+t_3 \times 2.0$  with the aid of a mold space adjusting material 20' to expand the polypropylene resin composition. Thus, a foamed base material layer 14 composed of the polypropylene resin composition is cooled and hardened under the pressurized condition while the mold space adjusting material 20' is being kept in a set state.



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